MOSFET – Power, N-Channel, SUPERFET III, Easy Drive

650 V, 6 A, 600 m Ω

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 474 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 11 \text{ nC}$)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 127 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

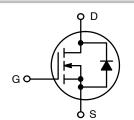
- Computing / Display Power Supplies
- Telecom / Server Power Supply
- Industrial Power Supplies
- Lighting / Charger / Adapter



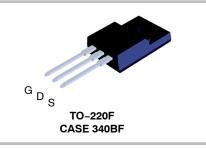
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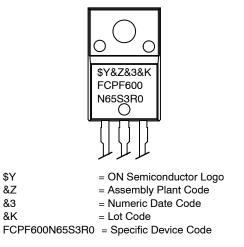
V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	600 mΩ @ 10 V	6 A



N-Channel MOSFET



MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Para	Value	Unit		
V _{DSS}	Drain to Source Voltage		650	V	
V _{GSS}	Gate to Source Voltage	DC	±30	V	
		AC (f > 1 Hz)	±30	V	
ID	Drain Current	Continuous (T _C = 25°C)	6*	A	
		Continuous (T _C = 100°C)	3.8*		
I _{DM}	Drain Current Pulsed (Note 1)		15*	А	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		24	mJ	
I _{AS}	Avalanche Current (Note 2)		1.6	A	
E _{AR}	Repetitive Avalanche Energy (Note 1)		0.24	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		20		
P _D	Power Dissipation	(T _C = 25°C)	24	W	
		Derate Above 25°C	0.19	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C	

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. *Drain current limited by maximum junction temperature.

1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. $I_{AS} = 1.6 \text{ A}, R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 3 \text{ A}$, di/dt $\le 200 \text{ A}/\mu\text{s}, V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	FCPF600N65S3R0L	Unit
R _{0JC}	Thermal Resistance, Junction to Case, Max.	5.29	°C/W
R _{0JA}	Thermal Resistance, Junction to Ambient, Max.	62.5	0/00

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF600N65S3R0L	FCPF600N65S3R0	TO-220F	Tube	N/A	N/A	50 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS	•	•	•	•	•
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I _D = 1 mA, T _J = 25°C	650	-	-	V
		V_{GS} = 0 V, I_{D} = 1 mA, T_{J} = 150°C	700	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to 25°C	-	0.66	-	V/°C
I _{DSS} Zer	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	1	μA
		V_{DS} = 520 V, T_{C} = 125°C	-	0.3	-	
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
ON CHARACTE	RISTICS					•
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 0.12 \text{ mA}$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 3 A	-	474	600	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 3 A	-	3.6	-	S
OYNAMIC CHA	RACTERISTICS	•				
C _{iss}	Input Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 1 MHz	-	465	-	pF
C _{oss}	Output Capacitance		-	10	-	pF
C _{oss(eff.)}	Effective Output Capacitance	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$	-	127	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	17	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	$V_{DS} = 400 \text{ V}, I_D = 3 \text{ A}, V_{GS} = 10 \text{ V}$	-	11	-	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	-	3	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	4.9	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.9	-	Ω
WITCHING CH	IARACTERISTICS		•			
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 3 \text{ A},$	-	11	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10 V, R _g = 4.7 Ω (Note 4)	-	9	-	ns
t _{d(off)}	Turn-Off Delay Time		-	29	-	ns
t _f	Turn-Off Fall Time		-	14	-	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS	•				
۱ _S	Maximum Continuous Source to Drain Diode Forward Current		-	-	6	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	15	А
V _{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 3 A	_	-	1.2	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 3 A,$	-	198	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/µs	_	1.6	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

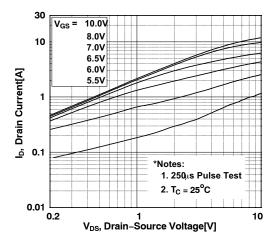


Figure 1. On-Region Characteristics

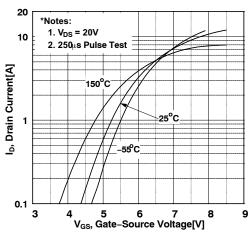


Figure 2. Transfer Characteristics

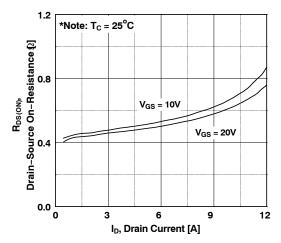


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

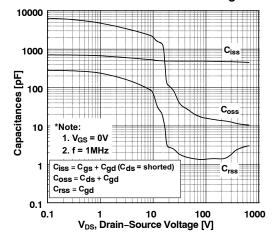


Figure 5. Capacitance Characteristics

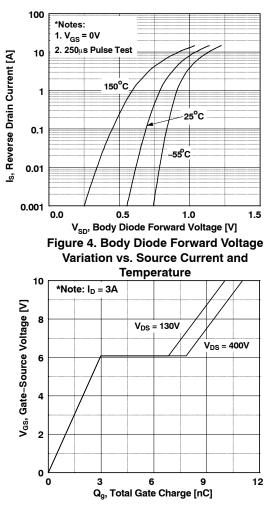
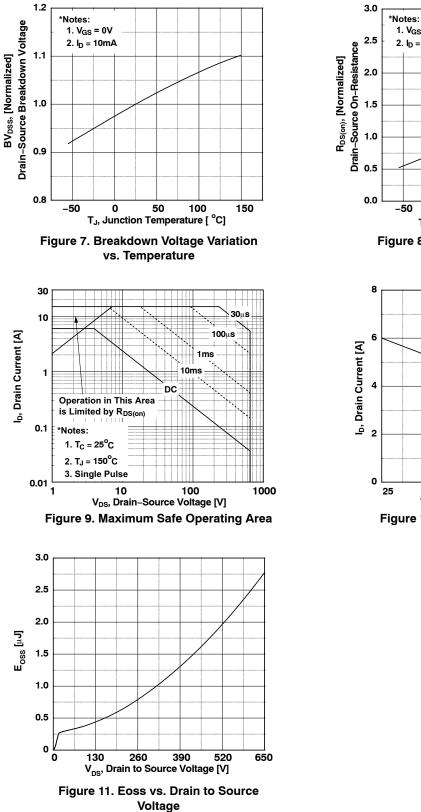
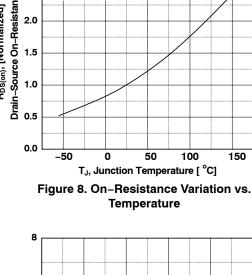


Figure 6. Gate Charge Characteristics

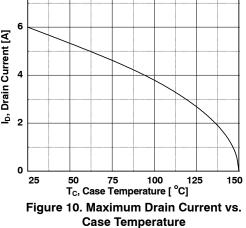
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)





1. V_{GS} = 10V

2. I_D = 3A



TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

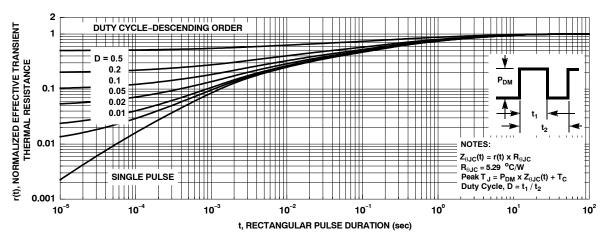
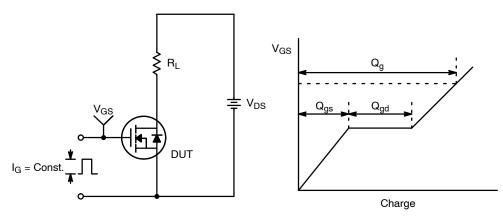


Figure 12. Transient Thermal Response Curve





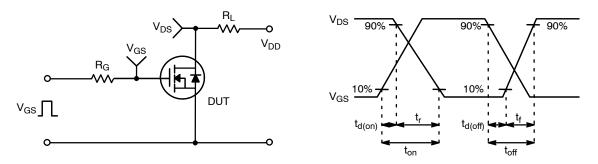


Figure 14. Resistive Switching Test Circuit & Waveforms

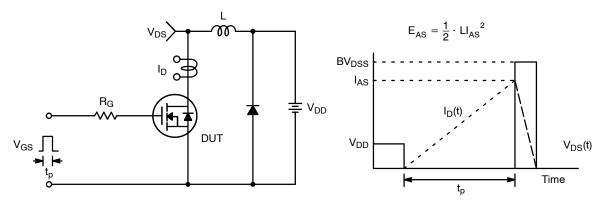


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

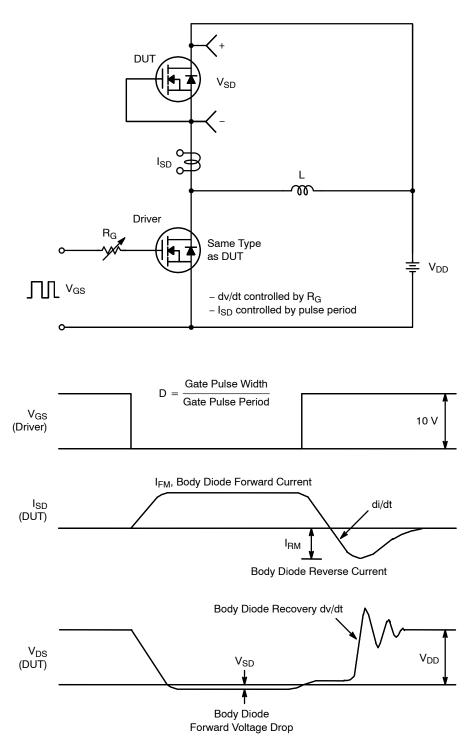


Figure 16. Peak Diode Recovery dt/dt Test Circuit & Waveforms

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TO-220 FULLPAK 3LD CASE 340BF **ISSUE O** DATE 31 AUG 2016 10.30 Α 9.80 2.90 Ø3.40 3.00 2.50 6.60 6.20 3.00 ++2.60 B 19.00 1 X 45° <u>B</u> 15.70 15.00 3.30 B 3 1 2.70 (2.14) 1.20 0.90(2X) 2.30 10.70 10.30 B 0.60 0.40 0.90 (3X) 0.50 1.20 $\oplus 0.50$ M Α NOTES: 2.74 (2X) 2.34 A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A. DOES NOT COMPLY EIAJ STD. VALUE. C. ALL DIMENSIONS ARE IN MILLIMETERS. D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS. E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009. <u>mn mm</u> 4.60 ПП 4.30

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